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Abstract of the Disclosure

Please insert new page 11 attached as **Exhibit A** hereto which sets forth an Abstract of the Disclosure.

LEAD FRAME PLATING APPARATUS

ABSTRACT OF THE DISCLOSURE

Disclosed herein is a lead frame plating apparatus. The lead frame plating apparatus comprises side inlets provided in the diagonal direction at opposite sides for supplying plating solution, a flow mixing room defined with an inner space in the longitudinal direction, a plating solution outlet for guiding the plating solution in the direction of nozzles, and a plating solution distribution part provided with the nozzles at an upper part of the plating solution outlet. Each nozzle is provided, at the lower end thereof, with a divergent-shaped expansion tube such that an inner diameter of the inlet of the expansion tube, larger than that of the nozzle, gradually decreases to an extent of the inner diameter of the nozzle. The lead frame plating apparatus supplies the plating solution through the nozzles with a uniform distribution.